

MEC1-120-02-F-D-A MEC1-130-02-F-D-A MEC1-140-02-L-D **MEC1 SERIES**

(1,00 mm) .0394"

EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material: Black LCF

Contact Material:

R_PCu

Plating: Sn or Au over 50μ"

(1,27 µm) Ni Operating Temp Range: -55°C to +125°C

Current Rating:

2.2 A per pin (2 adjacent pins powered) Voltage Rating: 300 VAC

Insertion Depth: (5,84 mm) .230" to (8,13 mm) .320"

RoHS Compliant:

Processing:

Lead-Free Solderable:

SMT Lead Coplanarity: (0,10 mm) .004" max (05-20) (0,15 mm) .006" max (30-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
- Other platings Contact Samtec

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information

Important Note:

Samtec recommends that pads on the mating board be Gold plated.

Note: Some sizes, styles and options are non-standard, non-returnable.

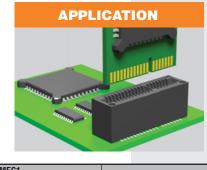
Mates with:

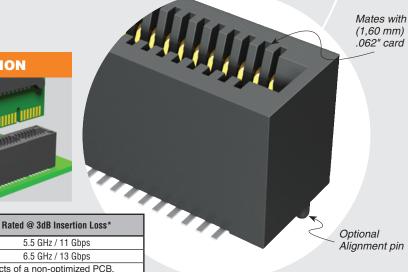
(1,60 mm) .062" card

9,04 mm Stack Height

Single-Ended Signaling

Differential Pair Signaling





*Performance data includes effects of a non-optimized PCB. Complete test data available at www.samtec.com?MEC1 or contact sig@samtec.com

POSITIONS

PER ROW



05, 08, 20, 30, 40, 50, 60, 70

02

= Gold flash on contact. Matte tin on tail

PLATING

OPTION

= 10µ" (0,25 µm) Gold on contact. Matte Tin on tail

POSITIONS

PER ROW

05

08

20

30

40

50

60

-NP = No Polarization (05, 08, 20 & 30 positions only)

Leave Blank for polarization

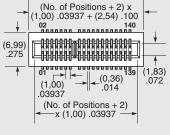
–A = Alignment Pin metal or plastic at Samtec discretion.

OTHER

OPTION

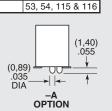
= (7,87 mm) .310" DIA Polyimide film Pick & Place Pad

–TR = Tape & Reel









POLARIZED

POSITIONS

(No Contact)

5, 6

15.16

21, 22

31, 32

41, 42

31, 32, 63 & 64